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Product data sheet

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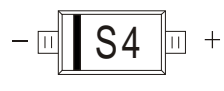
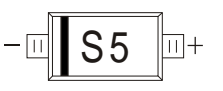
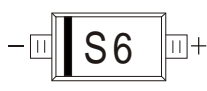
SOD-323



**FEATURES**

- Low Forward Voltage Drop
- Guard Ring Construction for Transient Protection
- Negligible Reverse Recovery Time
- Low Reverse Capacitance

**MARKING:**

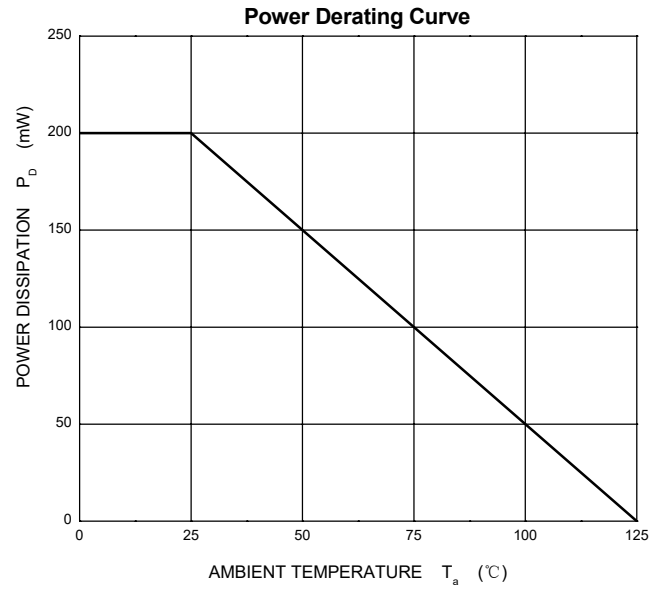
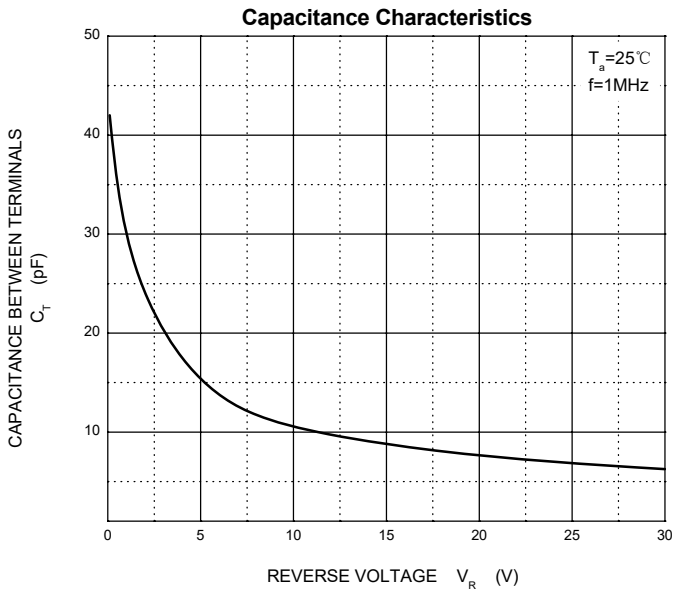
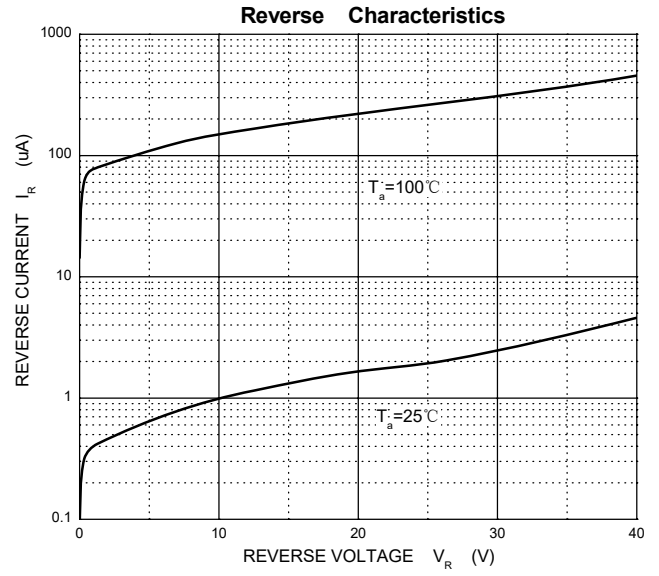
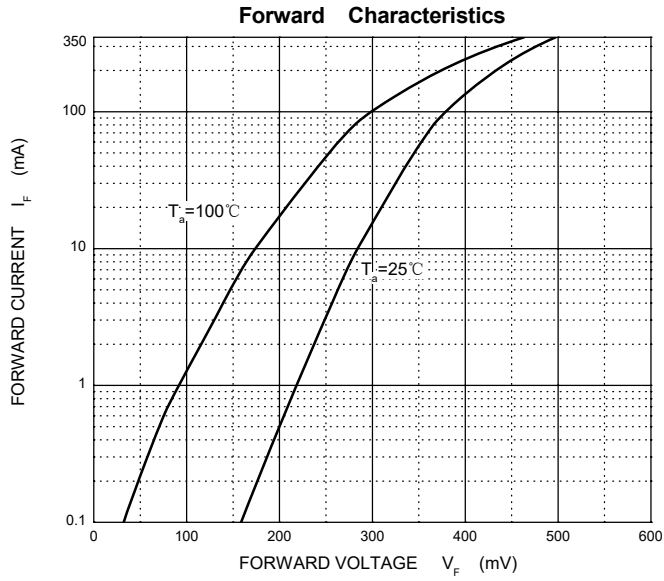
SD103AWS:S4	SD103BWS:S5	SD103CWS:S6
		

**Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25°C**

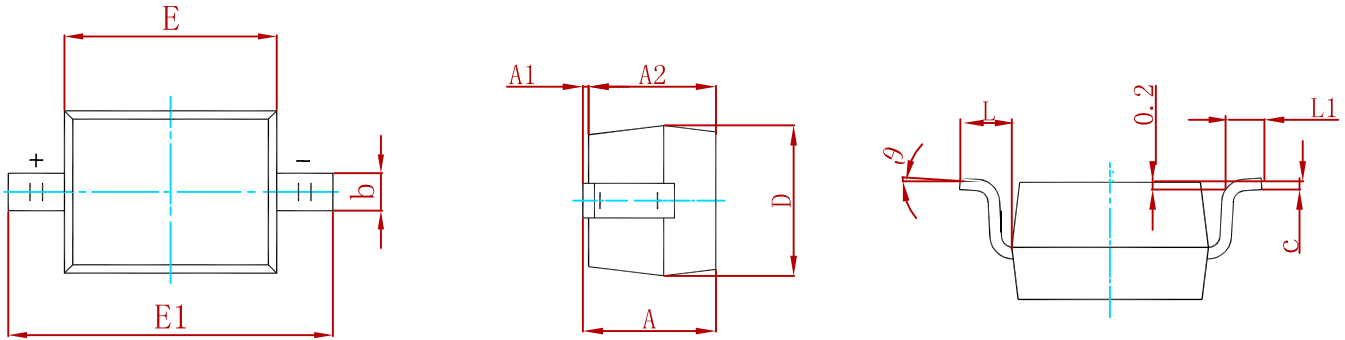
Parameter	Symbol	SD103AWS	SD103BWS	SD103CWS	Unit
Peak Repetitive Peak Reverse Voltage	$V_{RRM}$				
Working Peak Reverse Voltage	$V_{RWM}$	40	30	20	V
DC Blocking Voltage	$V_R$				
RMS Reverse Voltage	$V_{R(RMS)}$	28	21	14	V
Forward Continuous Current	$I_{FM}$	350			mA
Peak Repetitive Peak Forward Surge Current @t1, " a s	$I_{FSM}$	2.0			A
Power Dissipation	$P_d$	200			mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	500			°C/W
Junction Temperature	$T_j$	-40~+125			°C
Storage Temperature	$T_{STG}$	-55~+150			°C

**Electrical Ratings @Ta=25°C**

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Reverse breakdown voltage	$V_{(BR)}$	40			V	$I_R=100\mu A$
SD103AWS		30				$I_R=100\mu A$
SD103BWS		20				$I_R=100\mu A$
Forward voltage	$V_F$			0.37 0.60	V	$I_F=20mA$ $I_F=200mA$
Reverse current	$I_{RM}$			5.0		$\mu A$
SD103AWS						
SD103BWS						
Capacitance between terminals	$C_T$			50	pF	$V_R=0V, f=1.0MHz$
Reverse recovery time	$t_{rr}$		10		ns	$I_F=I_R=200mA$ $I_{rr}=0.1 \times I_R, R_L=100\Omega$
SD103CWS						

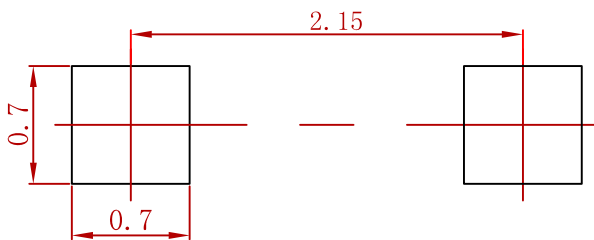


**PACKAGE MECHANICAL DATA**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

**Suggested Pad Layout**



- Note:**
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05\text{mm}$ .
  3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
SD103AWS-SD103CWS	SOD-323	3000

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